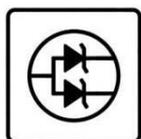


MSKSEMI 美森科

SEMICONDUCTOR



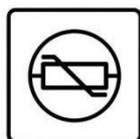
ESD



TVS



TSS



MOV



GDT



PLED

RS2MW(MS)

Product specification

Surface Mount Fast Recovery Rectifiers
Reverse Voltage - 50 to 1000 V
Forward Current - 2 A

PACKAGE OUTLINE	PINNING		Marking
 	PIN	DESCRIPTION	
	1	Cathode	
	2	Anode	

Features

- FEATURES
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Ideal for automated placement
- Fast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/ EU directives

MECHANICAL DATA

- Case: SOD- 123FL
- Terminals: Solderable per MIL-STD-750 , Method 2026
- Approx. Weight:15mg 0 .00053oz

Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20% .

Parameter	Symbols	Value	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ }^\circ\text{C}$	$I_{F(AV)}$	2	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	50	A
Maximum Forward Voltage at 2 A	V_F	1.3	V
Maximum DC Reverse Current $T_a = 25\text{ }^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125\text{ }^\circ\text{C}$	I_R	5 100	μA
Typical Junction Capacitance at $V_R=4\text{V}$, $f=1\text{MHz}$	C_j	30	pF
Maximum Reverse Recovery Time (1)	t_{rr}	500	ns
Typical Thermal Resistance (2)	$R_{\theta JA}$ $R_{\theta JC}$	75 22	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ\text{C}$

(1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) P.C.B . mounted with 2 .0" X 2 .0" (5 X 5 cm) copper pad areas .

Fig.1 Forward Current Derating Curve

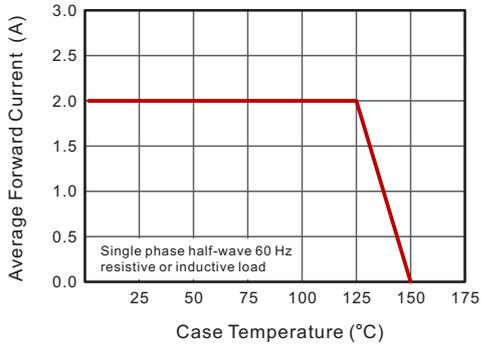


Fig.2 Typical Reverse Characteristics

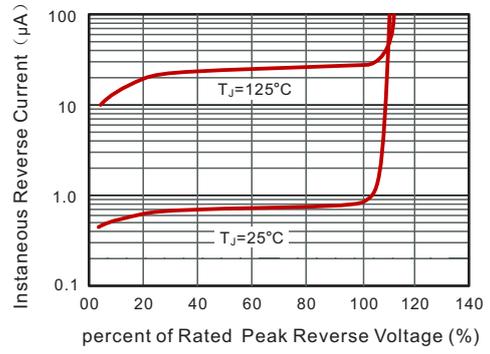


Fig.3 Typical Instantaneous Forward Characteristics

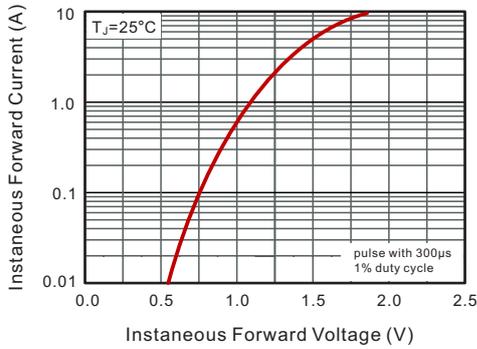


Fig.4 Typical Junction Capacitance

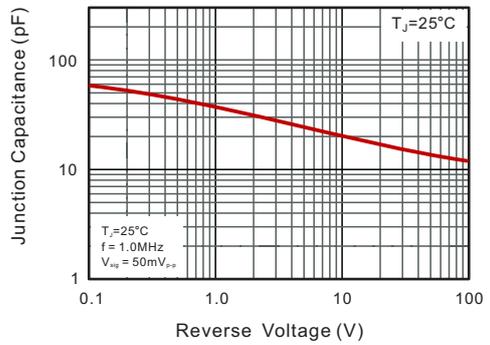
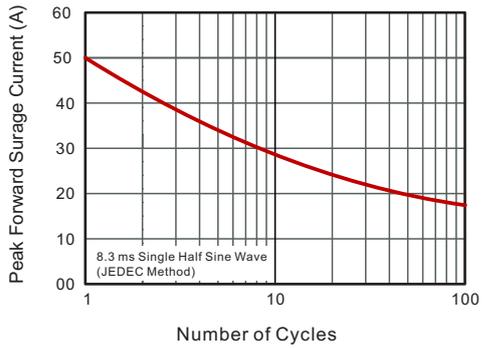
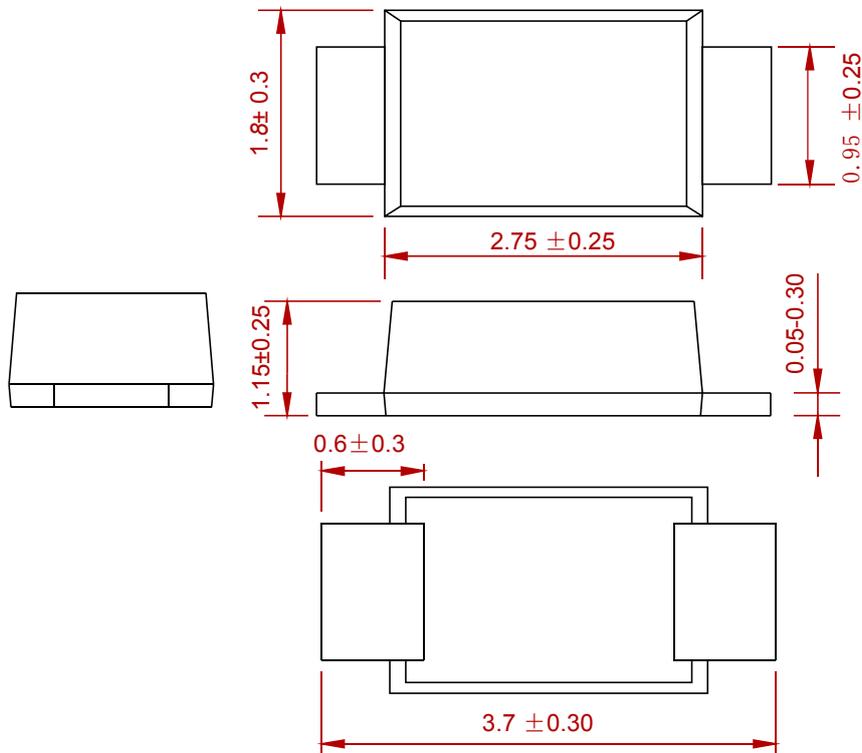


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

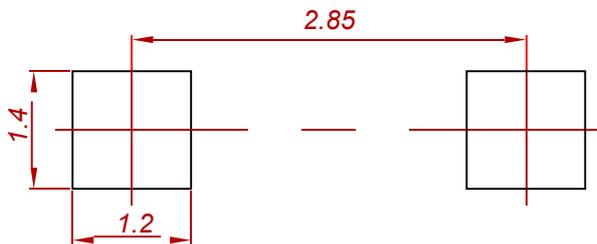


PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ± 0.05 mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RS2MW(MS)	SOD-123FL	3000

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